Features

- Fast Read Access Time 45 ns
- Low-Power CMOS Operation
 - 100 µA Max Standby
 - 20 mA Max Active at 5 MHz
- JEDEC Standard Packages
 - 28-lead PDIP
 - 32-lead PLCC
 - 28-lead TSOP and SOIC
- 5V ± 10% Supply
- High-Reliability CMOS Technology
 - 2.000V ESD Protection
 - 200 mA Latchup Immunity
- Rapid Programming Algorithm 100 µs/Byte (Typical)
- CMOS and TTL Compatible Inputs and Outputs
- Integrated Product Identification Code
- Industrial and Automotive Temperature Ranges
- Green (Pb/Halide-free) Packaging Option

1. Description

The AT27C512R is a low-power, high-performance 524,288-bit one-time programmable read-only memory (OTP EPROM) organized 64K by 8 bits. It requires only one 5V power supply in normal read mode operation. Any byte can be accessed in less than 45 ns, eliminating the need for speed reducing WAIT states on high-performance microprocessor systems.

Atmel's scaled CMOS technology provides high-speed, lower active power consumption, and significantly faster programming. Power consumption is typically only 8 mA in Active Mode and less than 10 μ A in Standby.

The AT27C512R is available in a choice of industry-standard JEDEC-approved one-time programmable (OTP) plastic PDIP, PLCC, SOIC, and TSOP packages. All devices feature two-line control ($\overline{\text{CE}}$, $\overline{\text{OE}}$) to give designers the flexibility to prevent bus contention.

With 64K byte storage capability, the AT27C512R allows firmware to be stored reliably and to be accessed by the system without the delays of mass storage media.

Atmel's AT27C512R has additional features to ensure high quality and efficient production use. The Rapid Programming Algorithm reduces the time required to program the part and guarantees reliable programming. Programming time is typically only 100 μ s/byte. The Integrated Product Identification Code electronically identifies the device and manufacturer. This feature is used by industry-standard programming equipment to select the proper programming algorithms and voltages.



512K (64K x 8) OTP EPROM

AT27C512R







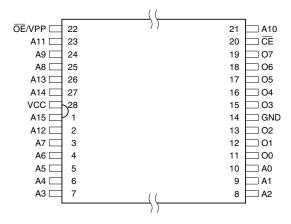
2. Pin Configurations

| Pin Name | Function |
|----------|-------------------------------|
| A0 - A15 | Addresses |
| 00 - 07 | Outputs |
| CE | Chip Enable |
| ŌĒ/VPP | Output Enable/ Program Supply |
| NC | No Connect |

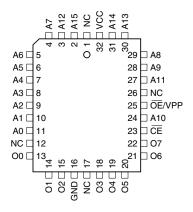
2.1 28-lead PDIP/SOIC Top View



2.3 28-lead TSOP Top View - Type 1



2.2 32-lead PLCC Top View

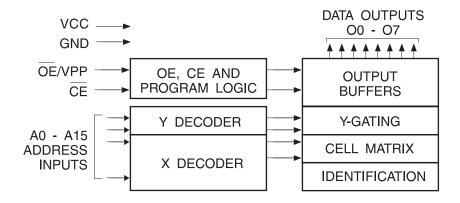


Note: PLCC Package Pins 1 and 17 are Don't Connect.

3. System Considerations

Switching between active and standby conditions via the Chip Enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed datasheet limits, resulting in device non-conformance. At a minimum, a 0.1 μF high frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the V_{CC} and Ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply voltage level on printed circuit boards with large EPROM arrays, a 4.7 μF bulk electrolytic capacitor should be utilized, again connected between the V_{CC} and Ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

4. Block Diagram



5. Absolute Maximum Ratings*

| Temperature Under Bias55°C to + 125°C |
|---|
| Storage Temperature65°C to + 150°C |
| Voltage on Any Pin with Respect to Ground2.0V to + 7.0V ⁽¹⁾ |
| Voltage on A9 with Respect to Ground2.0V to + 14.0V ⁽¹⁾ |
| V _{PP} Supply Voltage with Respect to Ground2.0V to + 14.0V ⁽¹⁾ |

*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note: 1. Minimum voltage is -0.6V DC which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is V_{CC} + 0.75V DC which may overshoot to +7.0 volts for pulses of less than 20 ns.



Operating Modes

| Mode/Pin | CE | OE/V _{PP} | Ai | Outputs |
|---------------------------------------|-----------------|--------------------|---|---------------------|
| Read | V _{IL} | V _{IL} | Ai | D _{OUT} |
| Output Disable | V _{IL} | V _{IH} | X ⁽¹⁾ | High Z |
| Standby | V _{IH} | X ⁽¹⁾ | X | High Z |
| Rapid Program ⁽²⁾ | V _{IL} | V _{PP} | Ai | D _{IN} |
| PGM Inhibit | V _{IH} | V _{PP} | X ⁽¹⁾ | High Z |
| Product Identification ⁽⁴⁾ | V _{IL} | V _{IL} | $A9 = V_{H}^{(3)}$ $A0 = V_{IH} \text{ or } V_{IL}$ $A1 - A15 = V_{IL}$ | Identification Code |

- Notes: 1. X can be V_{IL} or V_{IH} .
 - 2. Refer to Programming Characteristics.
 - 3. $V_H = 12.0 \pm 0.5V$.
 - 4. Two identifier bytes may be selected. All Ai inputs are held low (V_{IL}) , except A9 which is set to V_H and A0 which is toggled low (V_{IL}) to select the Manufacturer's Identification byte and high (V_{IH}) to select the Device Code byte.

DC and AC Operating Conditions for Read Operation

| | | AT27C512R | | | |
|------------------------|-------|--------------|---------------|--|--|
| | | -45 | -70 | | |
| Operating Temp.(Case) | Ind. | -40°C - 85°C | -40°C - 85°C | | |
| | Auto. | | -40°C - 125°C | | |
| V _{CC} Supply | | 5V ± 10% | 5V ± 10% | | |

DC and Operating Characteristics for Read Operation

| Symbol | Parameter | Condition | | Min | Max | Units |
|--|--|---|-------|------|-----------------------|-------|
| 1 | Input Load Current | V 0V to V | Ind. | | ±1 | μΑ |
| I _{LI} | Input Load Current | $V_{IN} = 0V \text{ to } V_{CC}$ | Auto. | | ±5 | μΑ |
| | 0 | V 0V4-V | Ind. | | ±5 | μΑ |
| I _{LO} Output Leakage Current | | $V_{OUT} = 0V \text{ to } V_{CC}$ | Auto. | | ±10 | μA |
| | V (1) Ot | I_{SB1} (CMOS), $\overline{CE} = V_{CC \pm} 0.3V$ | | | 100 | μΑ |
| I _{SB} | V _{CC} ⁽¹⁾ Standby Current | I_{SB2} (TTL), \overline{CE} = 2.0 to V_{CC} , 0.5V | | | 1 | mA |
| I _{cc} | V _{CC} Active Current | $f = 5 \text{ MHz}, I_{OUT} = 0 \text{ mA}, \overline{CE} = V_{IL}$ | | | 20 | mA |
| V _{IL} | Input Low Voltage | | | -0.6 | 0.8 | V |
| V _{IH} | Input High Voltage | | | 2.0 | V _{CC} + 0.5 | V |
| V _{OL} | Output Low Voltage | I _{OL} = 2.1 mA | | 0.4 | ٧ | |
| V _{OH} | Output High Voltage | I _{OH} = -400 μA | 2.4 | | V | |

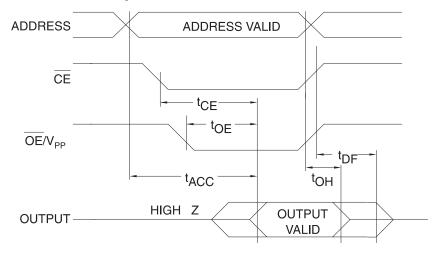
1. V_{CC} must be applied simultaneously with or before \overline{OE}/V_{PP} and removed simultaneously with or after \overline{OE}/V_{PP} . Note:

AC Characteristics for Read Operation

| | | | AT27C512R | | | | |
|---------------------------------|---|---|-----------|-----|-----|-----|-------|
| | | | -4 | -45 | | -70 | |
| Symbol | Parameter | Condition | Min | Max | Min | Max | Units |
| t _{ACC} ⁽¹⁾ | Address to Output Delay | $\overline{\text{CE}} = \overline{\text{OE}}/\text{V}_{\text{PP}} = \text{V}_{\text{IL}}$ | | 45 | | 70 | ns |
| t _{CE} ⁽¹⁾ | CE to Output Delay | $\overline{OE}/V_PP = V_IL$ | | 45 | | 70 | ns |
| t _{OE} ⁽¹⁾ | OE/V _{PP} to Output Delay | CE = V _{IL} | | 20 | | 30 | ns |
| t _{DF} ⁽¹⁾ | OE/V _{PP} or CE High to Output Float, Whichever Occurred First | | | 20 | | 25 | ns |
| t _{OH} | Output Hold from Address, CE or OE/V _{PP} Whichever Occurred First | | | | 7 | | ns |

1. See AC Waveforms for Read Operation. Note:

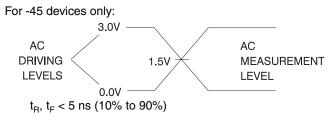
10. AC Waveforms for Read Operation⁽¹⁾



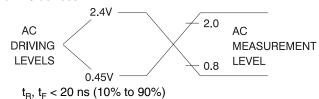
- Notes: 1. Timing measurement reference level is 1.5V for -45 devices. Input AC drive levels are $V_{IL} = 0.0V$ and $V_{IH} = 3.0V$. Timing measurement reference levels for all other speed grades are $V_{OL} = 0.8V$ and $V_{OH} = 2.0V$. Input AC drive levels are $V_{IL} = 0.45V$ and $V_{IH} = 2.4V$.
 - 2. $\overline{\text{OE}}/\text{V}_{PP}$ may be delayed up to t_{CE} t_{OE} after the falling edge of $\overline{\text{CE}}$ without impact on t_{CE} .
 - 3. \overline{OE}/V_{PP} may be delayed up to t_{ACC} t_{OE} after the address is valid without impact on t_{ACC} .
 - 4. This parameter is only sampled and is not 100% tested.
 - 5. Output float is defined as the point when data is no longer driven.



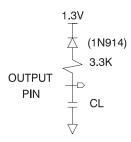
11. Input Test Waveforms and Measurement Levels



For -70 devices:



12. Output Test Load



Note: 1. $C_L = 100 \text{ pF}$ including jig capacitance, except for the -45 devices, where $C_L = 30 \text{ pF}$.

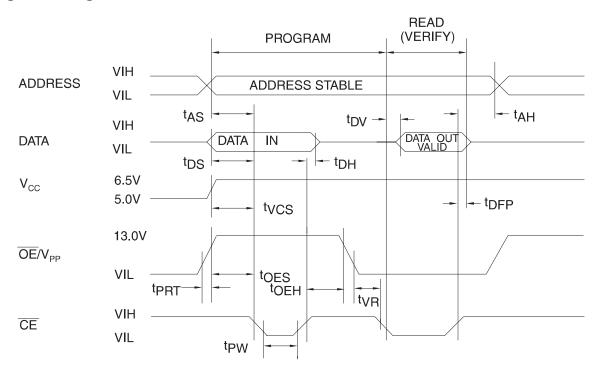
13. Pin Capacitance

 $f = 1 \text{ MHz}, T = 25^{\circ}C^{(1)}$

| Symbol | Тур | Max | Units | Conditions |
|------------------|-----|-----|-------|-----------------------|
| C _{IN} | 4 | 6 | pF | $V_{IN} = 0V$ |
| C _{OUT} | 8 | 12 | pF | V _{OUT} = 0V |

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.

14. Programming Waveforms⁽¹⁾



Notes: 1. The Input Timing Reference is 0.8V for $V_{\rm IL}$ and 2.0V for $V_{\rm IH}$.

2. t_{OE} and t_{DEP} are characteristics of the device but must be accommodated by the programmer.

15. DC Programming Characteristics

 $T_A = 25 \pm 5^{\circ}C, V_{CC} = 6.5 \pm 0.25V, \overline{OE}/V_{PP} = 13.0 \pm 0.25V$

| | | | Lin | Limits | |
|------------------|---|---------------------------|------|---------------------|-------|
| Symbol | Parameter | Test Conditions | Min | Max | Units |
| I _{LI} | Input Load Current | $V_{IN} = V_{IL}, V_{IH}$ | | ±10 | μΑ |
| V_{IL} | Input Low Level | | -0.6 | 0.8 | V |
| V_{IH} | Input High Level | | 2.0 | V _{CC} + 1 | V |
| V _{OL} | Output Low Voltage | I _{OL} = 2.1 mA | | 0.4 | V |
| V_{OH} | Output High Voltage | I _{OH} = -400 μA | 2.4 | | V |
| I _{CC2} | V _{CC} Supply Current (Program and Verify) | | | 25 | mA |
| I _{PP2} | OE/V _{PP} Current | CE = V _{IL} | | 25 | mA |
| V _{ID} | A9 Product Identification Voltage | | 11.5 | 12.5 | V |



16. AC Programming Characteristics

 $T_A = 25 \pm 5^{\circ}C$, $V_{CC} = 6.5 \pm 0.25V$, $\overline{OE}/V_{PP} = 13.0 \pm 0.25V$

| | | | Lin | nits | |
|------------------|--|---|-----|------|-------|
| Symbol | Parameter | Test Conditions ⁽¹⁾ | Min | Max | Units |
| t _{AS} | Address Setup Time | | 2 | | μs |
| t _{OES} | ŌE/V _{PP} Setup Time | | 2 | | μs |
| t _{OEH} | ŌĒ/V _{PP} Hold Time | Input Rise and Fall Times | 2 | | μs |
| t _{DS} | Data Setup Time | (10% to 90%) 20 ns | 2 | | μs |
| t _{AH} | Address Hold Time | Input Pulse Levels | 0 | | μs |
| t _{DH} | Data Hold Time | 0.45V to 2.4V | 2 | | μs |
| t _{DFP} | CE High to Output Float Delay ⁽²⁾ |] | 0 | 130 | ns |
| t _{VCS} | V _{CC} Setup Time | Input Timing Reference Level 0.8V to 2.0V | 2 | | μs |
| t _{PW} | CE Program Pulse Width ⁽³⁾ | 0.07 to 2.07 | 95 | 105 | μs |
| t _{DV} | Data Valid from $\overline{CE^{(2)}}$ | Output Timing Reference Level | | 1 | μs |
| t _{VR} | ŌĒ/V _{PP} Recovery Time | 0.8V to 2.0V | 2 | | μs |
| t _{PRT} | OE/V _{PP} Pulse Rise Time During Programming | | 50 | | ns |

Notes: 1. V_{CC} must be applied simultaneously or before \overline{OE}/V_{PP} and removed simultaneously or after \overline{OE}/V_{PP}

17. Atmel's AT27C512R Integrated Product Identification Code

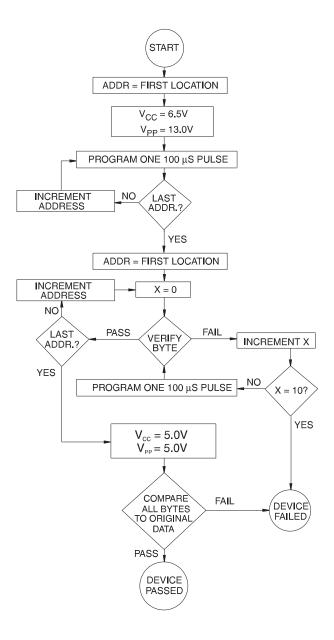
| | | Pins | | | | | | Hex | | |
|--------------|----|------|----|----|----|----|----|-----|----|------|
| Codes | Α0 | 07 | O6 | O5 | 04 | О3 | O2 | 01 | 00 | Data |
| Manufacturer | 0 | 0 | 0 | 0 | 1 | 1 | 1 | 1 | 0 | 1E |
| Device Type | 1 | 0 | 0 | 0 | 0 | 1 | 1 | 0 | 1 | 0D |

^{2.} This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is no longer driven – see timing diagram.

^{3.} Program Pulse width tolerance is 100 μ sec \pm 5%.

18. Rapid Programming Algorithm

A 100 μs \overline{CE} pulse width is used to program. The address is set to the first location. V_{CC} is raised to 6.5V and \overline{OE}/V_{PP} is raised to 13.0V. Each address is first programmed with one 100 μs \overline{CE} pulse without verification. Then a verification/reprogramming loop is executed for each address. In the event a byte fails to pass verification, up to 10 successive 100 μs pulses are applied with a verification after each pulse. If the byte fails to verify after 10 pulses have been applied, the part is considered failed. After the byte verifies properly, the next address is selected until all have been checked. \overline{OE}/V_{PP} is then lowered to V_{IL} and V_{CC} to 5.0V. All bytes are read again and compared with the original data to determine if the device passes or fails.







19. Ordering Information

19.1 Standard Package

| t _{ACC} | I _{cc} (| (mA) | | | |
|------------------|-------------------|------|----------------|---------|------------------|
| (ns) | | | Ordering Code | Package | Operation Range |
| 45 | 20 | 0.1 | AT27C512R-45JI | 32J | Industrial |
| | | | AT27C512R-45PI | 28P6 | (-40°C to 85°C) |
| | | | AT27C512R-45RI | 28R | |
| | | | AT27C512R-45TI | 28T | |
| 70 | 20 | 0.1 | AT27C512R-70JI | 32J | Industrial |
| | | | AT27C512R-70PI | 28P6 | (-40°C to 85°C) |
| | | | AT27C512R-70RI | 28R | |
| | | | AT27C512R-70TI | 28T | |
| | 20 | 0.1 | AT27C512R-70JA | 32J | Automotive |
| | | | AT27C512R-70PA | 28P6 | (-40°C to 125°C) |
| | | | AT27C512R-70RA | 28R | |

Note: Refer to PCN# SC042702.

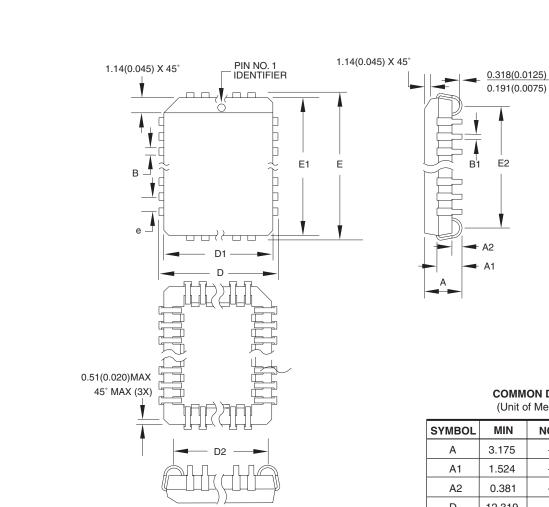
19.2 Green Package Option (Pb/Halide-free)

| t _{ACC} | I _{CC} (mA) | | | | |
|------------------|----------------------|---------|----------------|---------|-----------------|
| (ns) | Active | Standby | Ordering Code | Package | Operation Range |
| 45 | 20 | 0.1 | AT27C512R-45JU | 32J | Industrial |
| | | | AT27C512R-45RU | 28R | (-40°C to 85°C) |
| | | | AT27C512R-45TU | 28T | |
| 70 | 20 | 0.1 | AT27C512R-70JU | 32J | Industrial |
| | | | AT27C512R-70PU | 28P6 | (-40°C to 85°C) |

| | Package Type | | |
|------|--|--|--|
| 32J | 32-Lead, Plastic J-Leaded Chip Carrier (PLCC) | | |
| 28P6 | 28-Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP) | | |
| 28R | 28-Lead, 0.330" Wide, Plastic Gull Wing Small Outline (SOIC) | | |
| 28T | 28-Lead, Thin Small Outline Package (TSOP) | | |

Packaging Information

19.3 32J - PLCC



Notes:

- 1. This package conforms to JEDEC reference MS-016, Variation AE.
- Dimensions D1 and E1 do not include mold protrusion.
 Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
- 3. Lead coplanarity is 0.004" (0.102 mm) maximum.

COMMON DIMENSIONS

(Unit of Measure = mm)

| SYMBOL | MIN | NOM | MAX | NOTE |
|--------|--------|-----------|--------|--------|
| Α | 3.175 | _ | 3.556 | |
| A1 | 1.524 | _ | 2.413 | |
| A2 | 0.381 | _ | _ | |
| D | 12.319 | _ | 12.573 | |
| D1 | 11.354 | _ | 11.506 | Note 2 |
| D2 | 9.906 | _ | 10.922 | |
| Е | 14.859 | _ | 15.113 | |
| E1 | 13.894 | _ | 14.046 | Note 2 |
| E2 | 12.471 | _ | 13.487 | |
| В | 0.660 | _ | 0.813 | |
| B1 | 0.330 | _ | 0.533 | |
| е | | 1.270 TYF |) | |

10/04/01



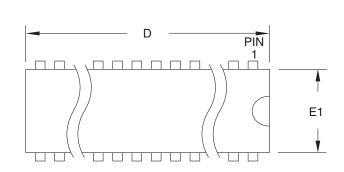
| TITLE | |
|-----------------------|--------------------------------------|
| 32J , 32-lead, | Plastic J-leaded Chip Carrier (PLCC) |

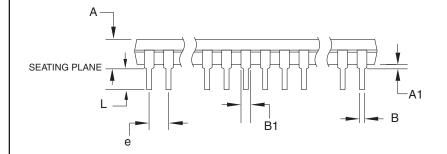
DRAWING NO. REV.

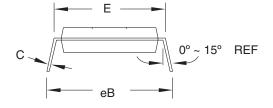




19.4 28P6 - PDIP







Notes:

- 1. This package conforms to JEDEC reference MS-011, Variation AB.
- Dimensions D and E1 do not include mold Flash or Protrusion. Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

COMMON DIMENSIONS

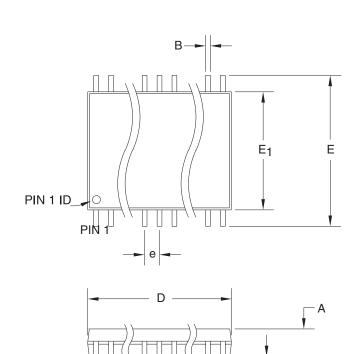
(Unit of Measure = mm)

| SYMBOL | MIN | NOM | MAX | NOTE |
|--------|-----------|-----|--------|--------|
| Α | _ | _ | 4.826 | |
| A1 | 0.381 | _ | _ | |
| D | 36.703 | _ | 37.338 | Note 2 |
| Е | 15.240 | _ | 15.875 | |
| E1 | 13.462 | _ | 13.970 | Note 2 |
| В | 0.356 | _ | 0.559 | |
| B1 | 1.041 | _ | 1.651 | |
| L | 3.048 | _ | 3.556 | |
| С | 0.203 | _ | 0.381 | |
| eB | 15.494 | _ | 17.526 | |
| е | 2.540 TYP | | | |
| | | | | |

09/28/01

| | TITLE | | DRAWING NO. | REV. |
|------------------------------|---------------|---|-------------|------|
| 2325 Orchard San Jose, CA | OC101 28P6, | 28-lead (0.600"/15.24 mm Wide) Plastic Dual Package (PDIP) | 28P6 | В |

19.5 28R - SOIC





Note: 1. Dimensions D and E1 do not include mold Flash or protrusion. Mold Flash or protrusion shall not exceed 0.25 mm (0.010").

COMMON DIMENSIONS

(Unit of Measure = mm)

| SYMBOL | MIN | NOM | MAX | NOTE |
|---------|--------|----------|----------|--------|
| OTHIDOL | | | 1117 171 | |
| Α | 2.39 | _ | 2.79 | |
| A1 | 0.050 | _ | 0.356 | |
| D | 18.00 | _ | 18.50 | Note 1 |
| E | 11.70 | _ | 12.50 | |
| E | 1 8.59 | _ | 8.79 | Note 1 |
| В | 0.356 | _ | 0.508 | |
| С | 0.203 | _ | 0.305 | |
| L | 0.94 | _ | 1.27 | |
| е | | 1.27 TYP | | |

5/18/2004

С



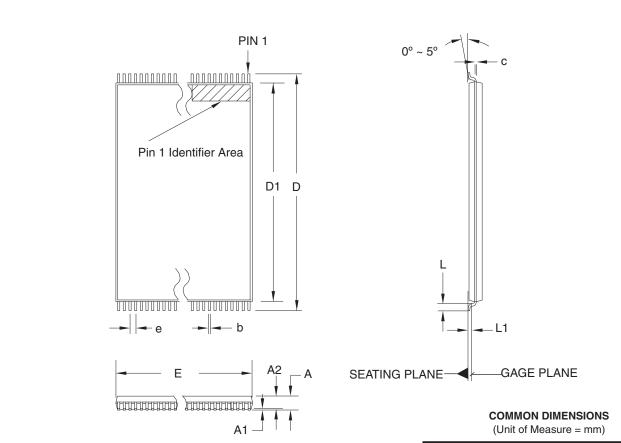
2325 Orchard Parkway San Jose, CA 95131

TITLE 28R, 28-lead, 0.330" Body Width, Plastic Gull Wing Small Outline (SOIC) DRAWING NO. REV. 28R





19.6 28T - TSOP



Notes:

- 1. This package conforms to JEDEC reference MO-183.
- 2. Dimensions D1 and E do not include mold protrusion. Allowable protrusion on E is 0.15 mm per side and on D1 is 0.25 mm per side.
- 3. Lead coplanarity is 0.10 mm maximum.

| (0) | | | | | |
|--------|------------|-------|-------|--------|--|
| SYMBOL | MIN | NOM | MAX | NOTE | |
| Α | _ | _ | 1.20 | | |
| A1 | 0.05 | - | 0.15 | | |
| A2 | 0.90 | 1.00 | 1.05 | | |
| D | 13.20 | 13.40 | 13.60 | | |
| D1 | 11.70 | 11.80 | 11.90 | Note 2 | |
| Е | 7.90 | 8.00 | 8.10 | Note 2 | |
| L | 0.50 | 0.60 | 0.70 | | |
| L1 | 0.25 BASIC | | | | |
| b | 0.17 | 0.22 | 0.27 | | |
| С | 0.10 | _ | 0.21 | | |
| е | 0.55 BASIC | | | | |
| | | | | | |

12/06/02

| | | DRAWING NO. | REV. |
|--|--|-------------|------|
| 2325 Orchard Parkway San Jose, CA 95131 | 28T , 28-lead (8 x 13.4 mm) Plastic Thin Small Outline Package, Type I (TSOP) | 28T | С |



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